



## Material Content Data Sheet



<b>Sales Product Name</b>		BSL207N H6327		<b>Issued</b>		19. July 2018		
<b>MA#</b>		MA001165084						
<b>Package</b>		PG-TSOP6-6-4		<b>Weight*</b>		14.84 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	non noble metal	tin	7440-31-5	0.009	0.06		595	
	noble metal	gold	7440-57-5	0.034	0.23		2306	
	inorganic material	silicon	7440-21-3	0.522	3.52	3.81	35174	38075
leadframe	inorganic material	silicon	7440-21-3	0.001	0.01		95	
	non noble metal	titanium	7440-32-6	0.007	0.05		477	
	non noble metal	chromium	7440-47-3	0.021	0.14		1431	
	non noble metal	copper	7440-50-8	7.048	47.50	47.70	474964	476967
wire	non noble metal	copper	7440-50-8	0.049	0.33	0.33	3275	3275
encapsulation	organic material	carbon black	1333-86-4	0.066	0.45		4452	
	plastics	epoxy resin	-	1.420	9.57		95721	
	inorganic material	silicondioxide	60676-86-0	5.120	34.50	44.52	345042	445215
leadfinish	non noble metal	tin	7440-31-5	0.392	2.64	2.64	26450	26450
plating	noble metal	silver	7440-22-4	0.149	1.00	1.00	10018	10018
*deviation	< 10%		Sum in total:			100.00		1000000

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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